HIGH PERFORMANCE CHIP PACKAGING AND METHOD

ABSTRACT

A chip carrier package (10) that includes a cover plate (20) attached to a stiffener (30) by a reflowable bonding material is disclosed. Additionally, a thermally and electrically conductive bonding material between the cover plate (20) and the chip (40) itself may be included. Also a chip package (10) including an alignment device (290) to aid in properly aligning the cover plate (20) on the stiffener (30) is disclosed. Furthermore, a method of packaging a chip including providing a reflowable material between the cover plate (20) and stiffener body (30) for attaching the cover plate (20) to the stiffener (30),and simultaneously attaching the cover plate (20) to the stiffener (30) when attaching the carrier (10) to an electric circuit board is disclosed.

Fig. 1

This Sheet Has Been Replaced



THIS SHEET HAS BEEN REPLACED